



IN THE U.S. PATENT AND TRADEMARK OFFICE

AF/2811

In re Application of: Yamaguchi, et al.

Serial No.: 10/087,556

Filed: 03/01/2002

For: Semiconductor Device and Bump Formation
Method

Docket No.: TI-31471

Examiner: Im, J.M.

Art Unit: 2811

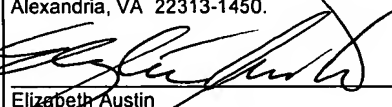
Conf. No.: 2191

12/10-6-02
Appeal Brief
[Signature]

APPEAL BRIEF TRANSMITTAL FORM

Commissioner for Patents
Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8 (A)	
I hereby certify that on this day this correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
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Transmitted herewith in triplicate is an Appellant's Brief in the above-identified application.

Charge any additional fees, or credit overpayment to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

Respectfully submitted,



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